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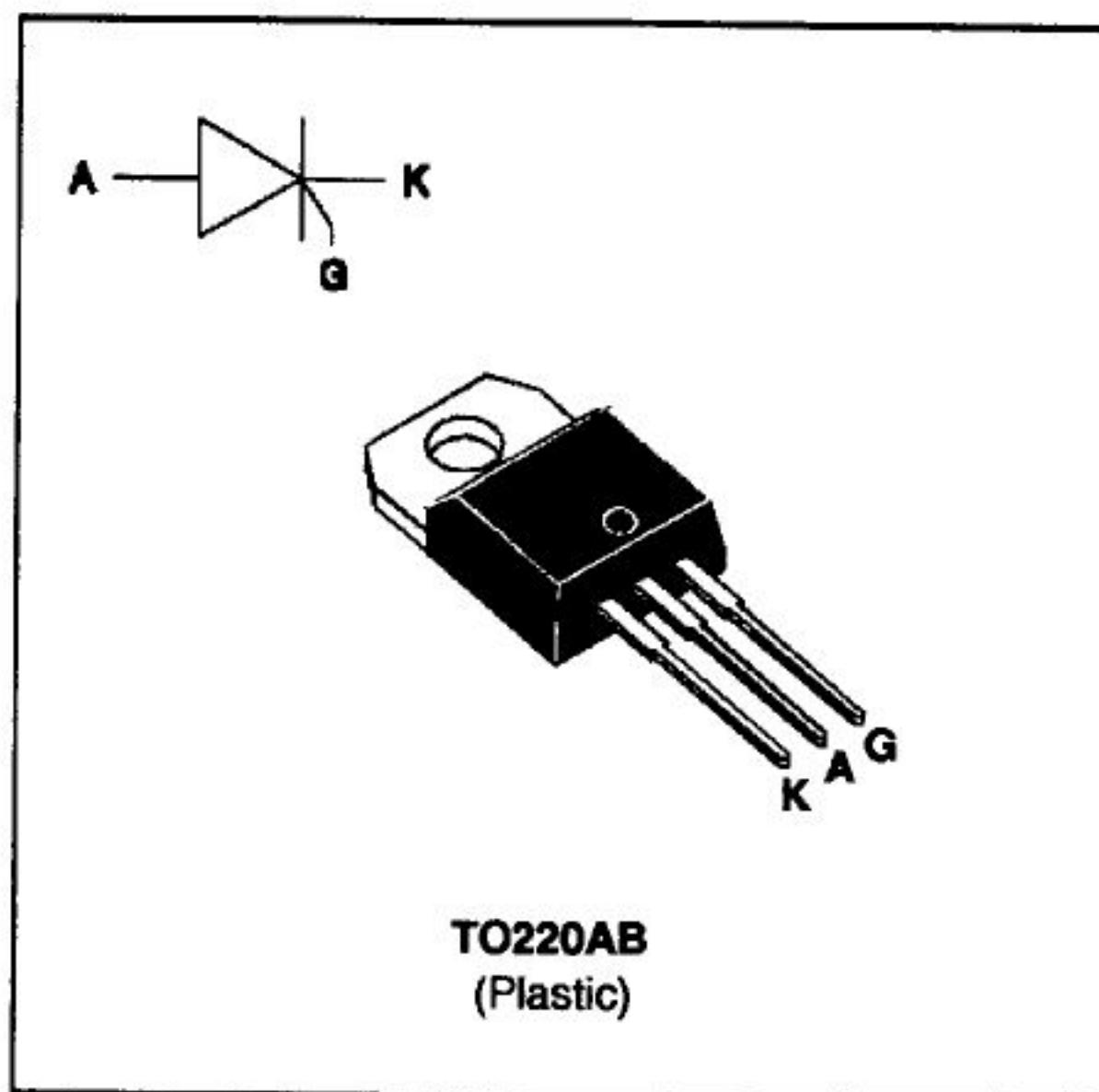
## FEATURES

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY

## DESCRIPTION

The TYN 204 ---> TYN 1004 Family of Silicon Controlled Rectifiers uses a high performance glass passivated technology.

This general purpose Family of Silicon Controlled Rectifiers is designed for power supplies up to 400Hz on resistive or inductive load.



## ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
$I_T(\text{RMS})$	RMS on-state current (180° conduction angle)	4	A	
$I_T(\text{AV})$	Average on-state current (180° conduction angle, single phase circuit)	2.5	A	
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_J$ initial = 25°C )	$t_p = 8.3 \text{ ms}$	63	A
		$t_p = 10 \text{ ms}$	60	
$I^2t$	$I^2t$ value	18	$\text{A}^2\text{s}$	
$dI/dt$	Critical rate of rise of on-state current Gate supply : $I_G = 100 \text{ mA}$ $dI_G/dt = 1 \text{ A}/\mu\text{s}$	100	$\text{A}/\mu\text{s}$	
$T_{stg}$ $T_J$	Storage and operating junction temperature range	- 40 to + 150 - 40 to + 125	$^{\circ}\text{C}$	
$T_l$	Maximum lead temperature for soldering during 10 s at 4.5 mm from case	260	$^{\circ}\text{C}$	

Symbol	Parameter	TYN					Unit
		204	404	604	804	1004	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_J = 125^{\circ}\text{C}$	200	400	600	800	1000	V

**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
R <sub>th</sub> (j-a)	Junction to ambient	60	°C/W
R <sub>th</sub> (j-c) DC	Junction to case for DC	2.5	°C/W

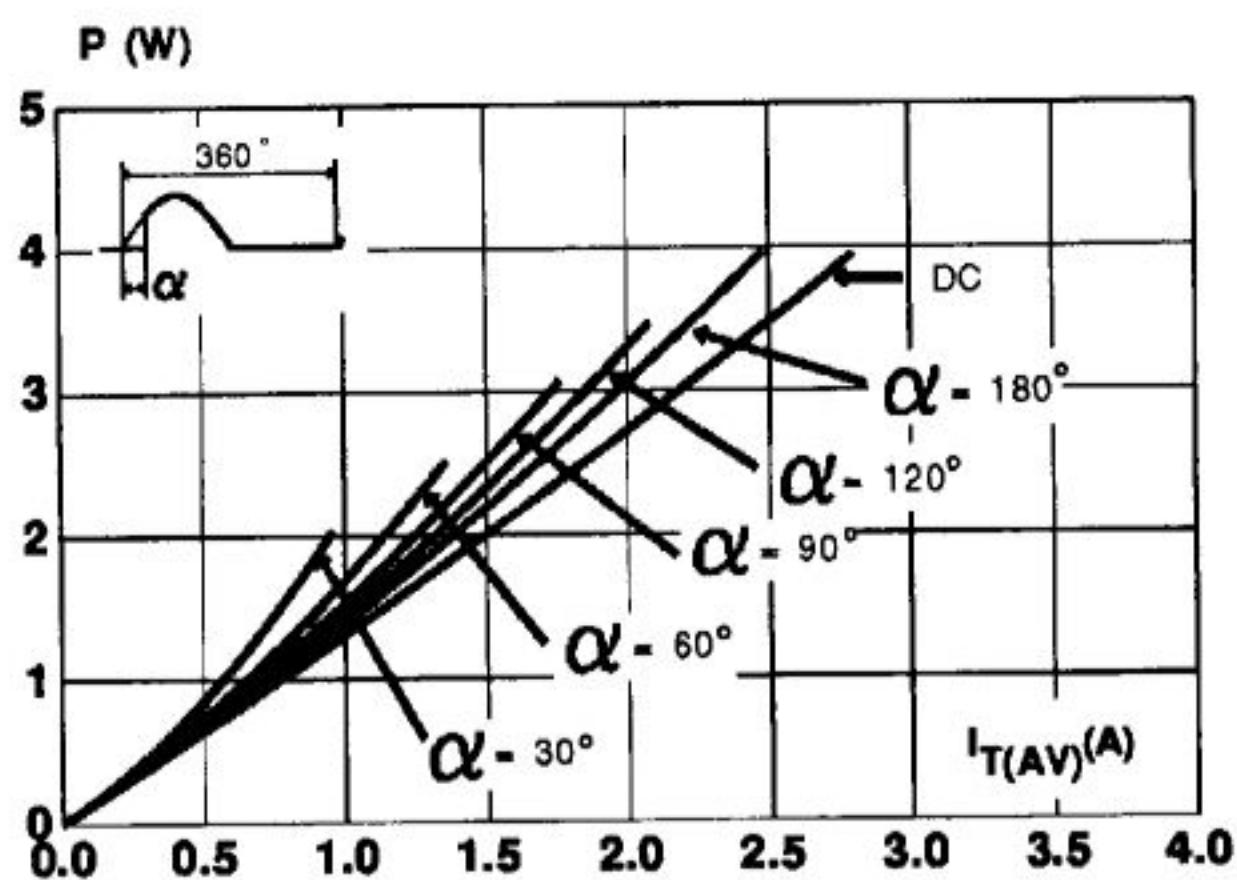
**GATE CHARACTERISTICS (maximum values)**

P<sub>G</sub> (AV) = 1W   P<sub>GM</sub> = 10W (t<sub>p</sub> = 20 μs)   I<sub>FGM</sub> = 4A (t<sub>p</sub> = 20 μs)   V<sub>RGM</sub> = 5 V.

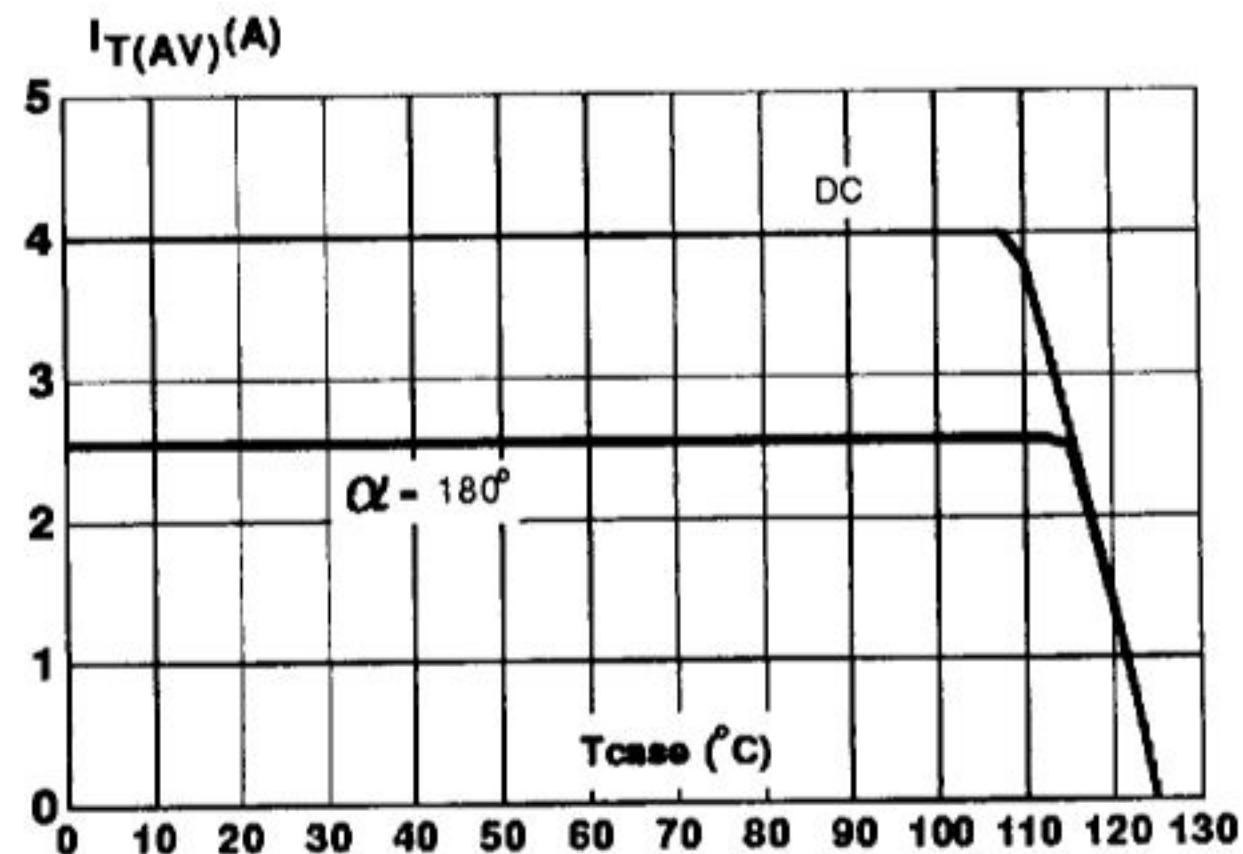
**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions		Value	Unit
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	MAX	15
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	MAX	1.5
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> = 110°C	MIN	0.2
t <sub>gt</sub>	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 40mA dI <sub>G</sub> /dt = 0.5A/μs	T <sub>j</sub> =25°C	TYP	2
I <sub>L</sub>	I <sub>G</sub> = 1.2 I <sub>GT</sub>	T <sub>j</sub> =25°C	TYP	50
I <sub>H</sub>	I <sub>T</sub> = 100mA gate open	T <sub>j</sub> =25°C	MAX	30
V <sub>TM</sub>	I <sub>TM</sub> = 8A t <sub>p</sub> = 380μs	T <sub>j</sub> =25°C	MAX	1.8
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>DRM</sub> Rated V <sub>RRM</sub> Rated	T <sub>j</sub> =25°C	MAX	0.01
		T <sub>j</sub> = 110°C		2
dV/dt	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	T <sub>j</sub> = 110°C	MIN	200
t <sub>q</sub>	V <sub>D</sub> =67%V <sub>DRM</sub> I <sub>TM</sub> = 8A V <sub>R</sub> = 25V dI <sub>TM</sub> /dt=30 A/μs dV <sub>D</sub> /dt= 50V/μs	T <sub>j</sub> = 110°C	TYP	70

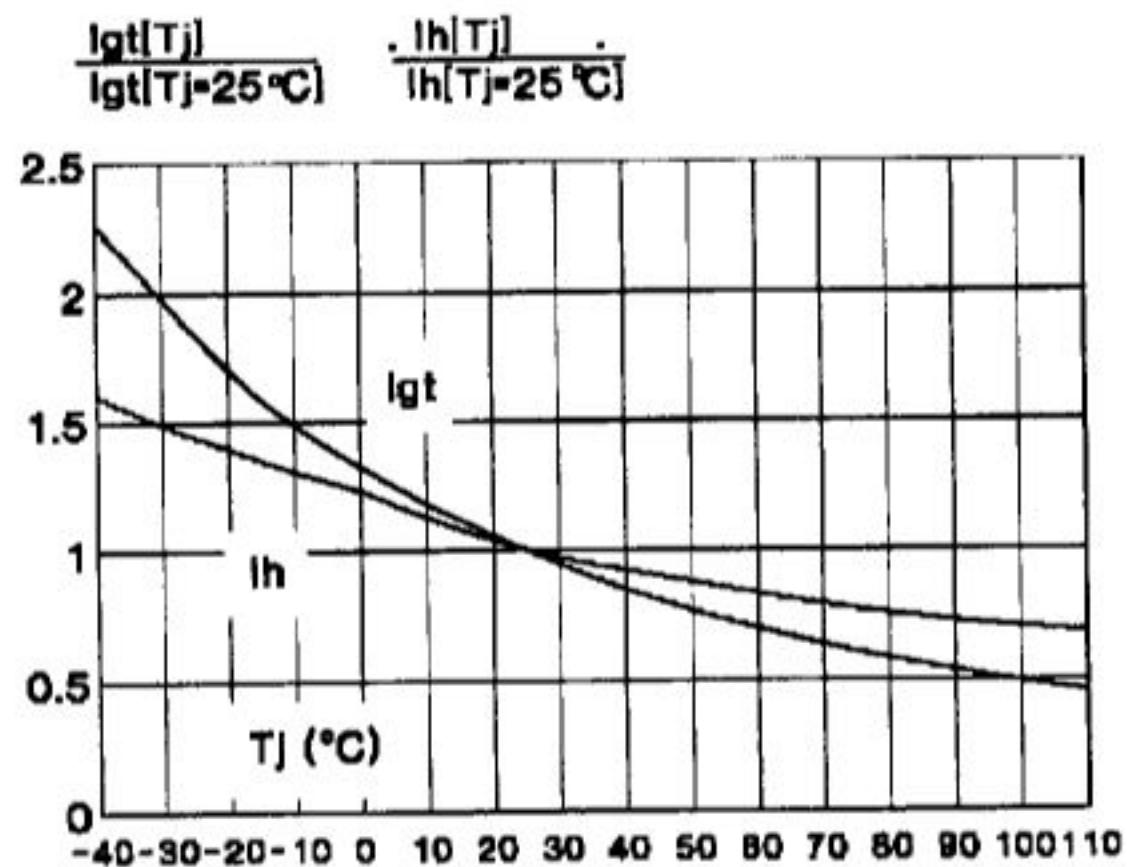
**Fig.1 :** Maximum average power dissipation versus average on-state current.



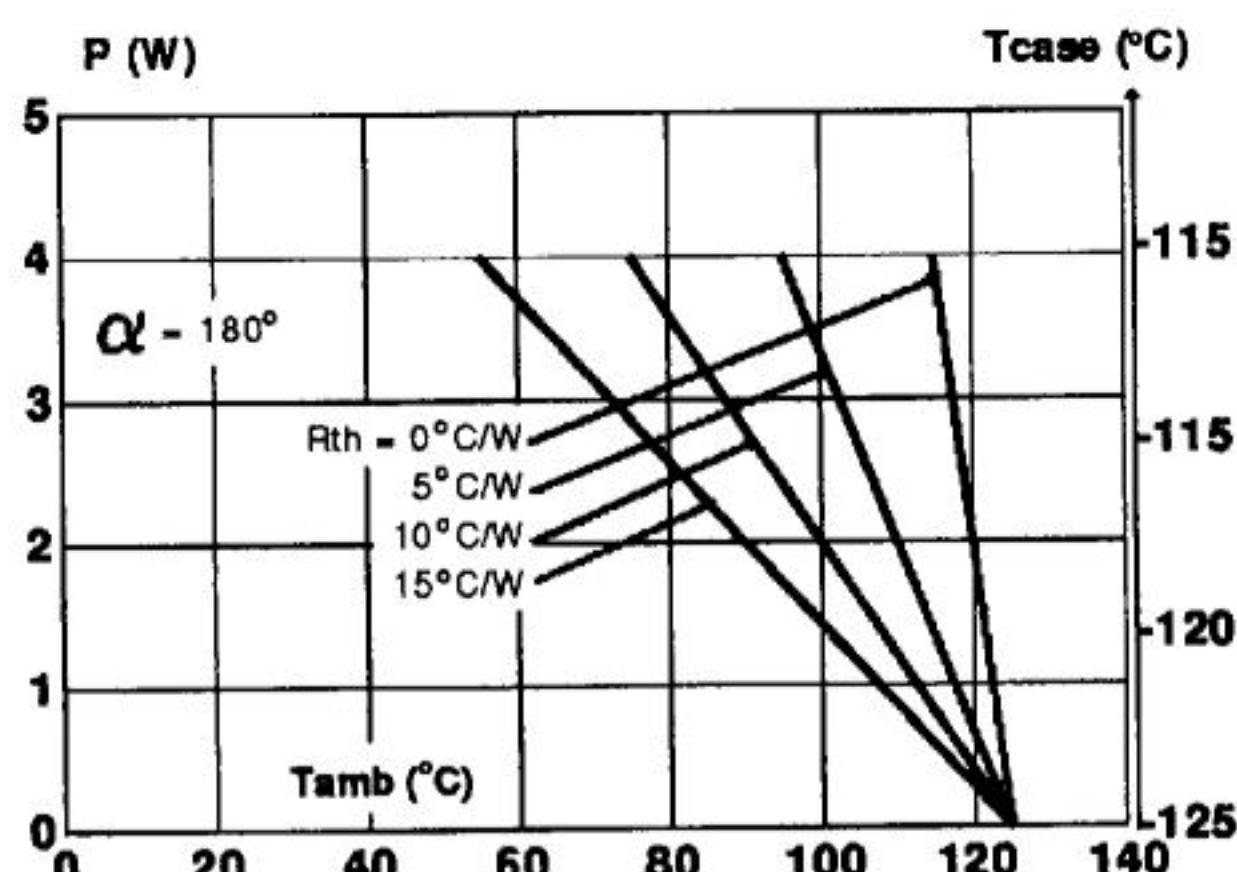
**Fig.3 :** Average on-state current versus case temperature.



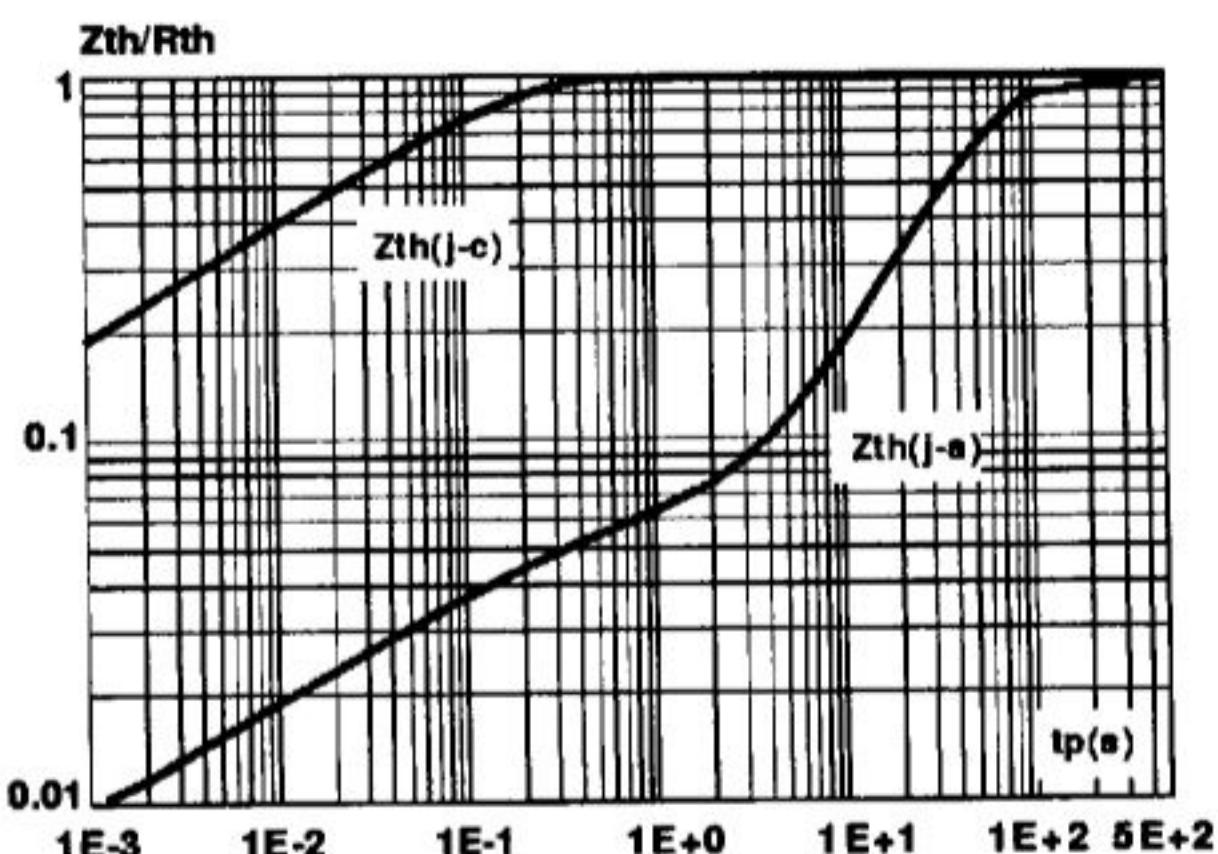
**Fig.5 :** Relative variation of gate trigger current versus junction temperature.



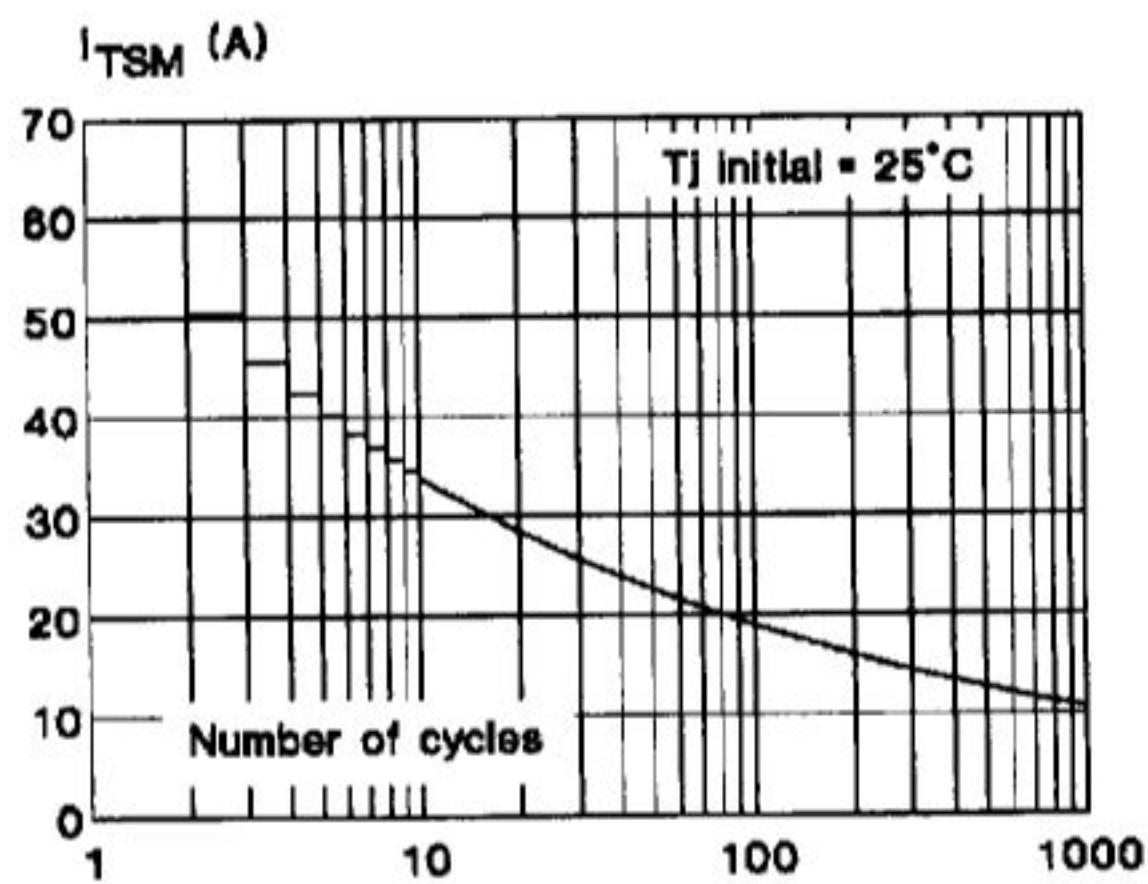
**Fig.2 :** Correlation between maximum average power dissipation and maximum allowable temperatures (Tamb and Tcase) for different thermal resistances heatsink + contact.



**Fig.4 :** Relative variation of thermal impedance versus pulse duration.

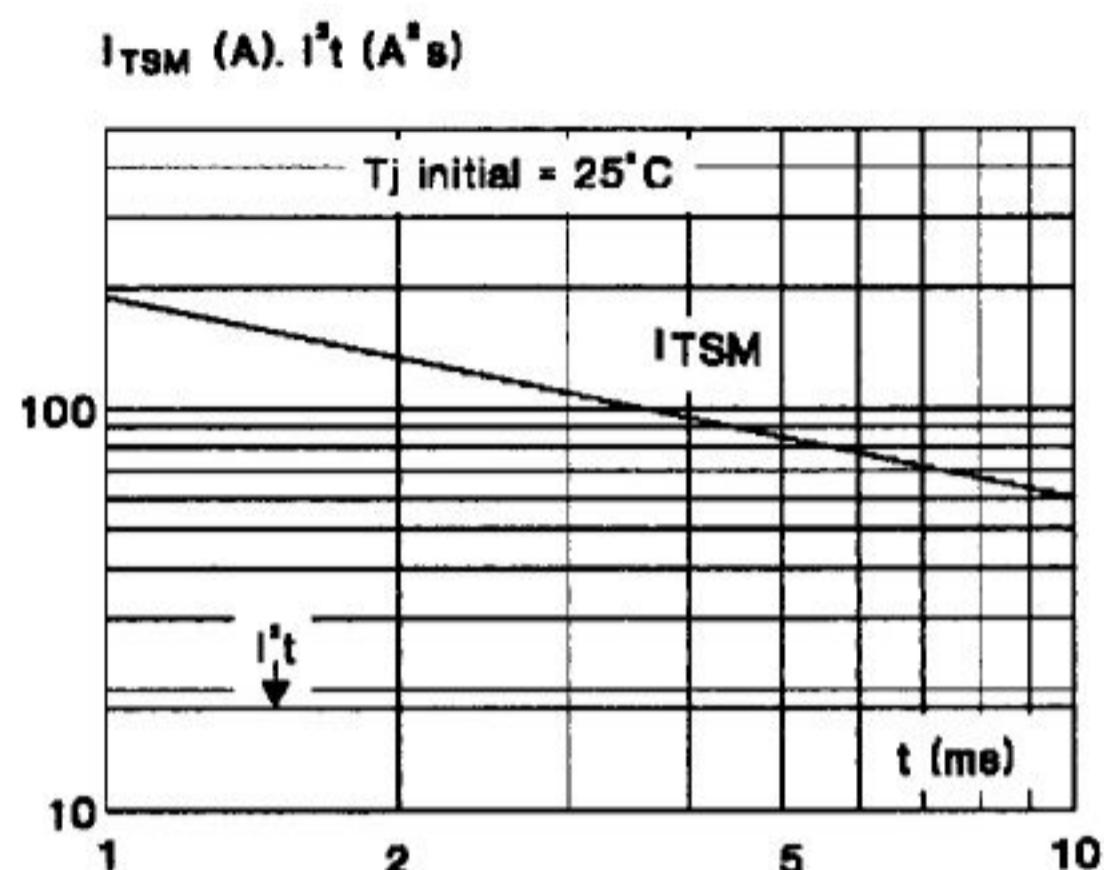


**Fig.6 :** Non repetitive surge peak on-state current versus number of cycles.

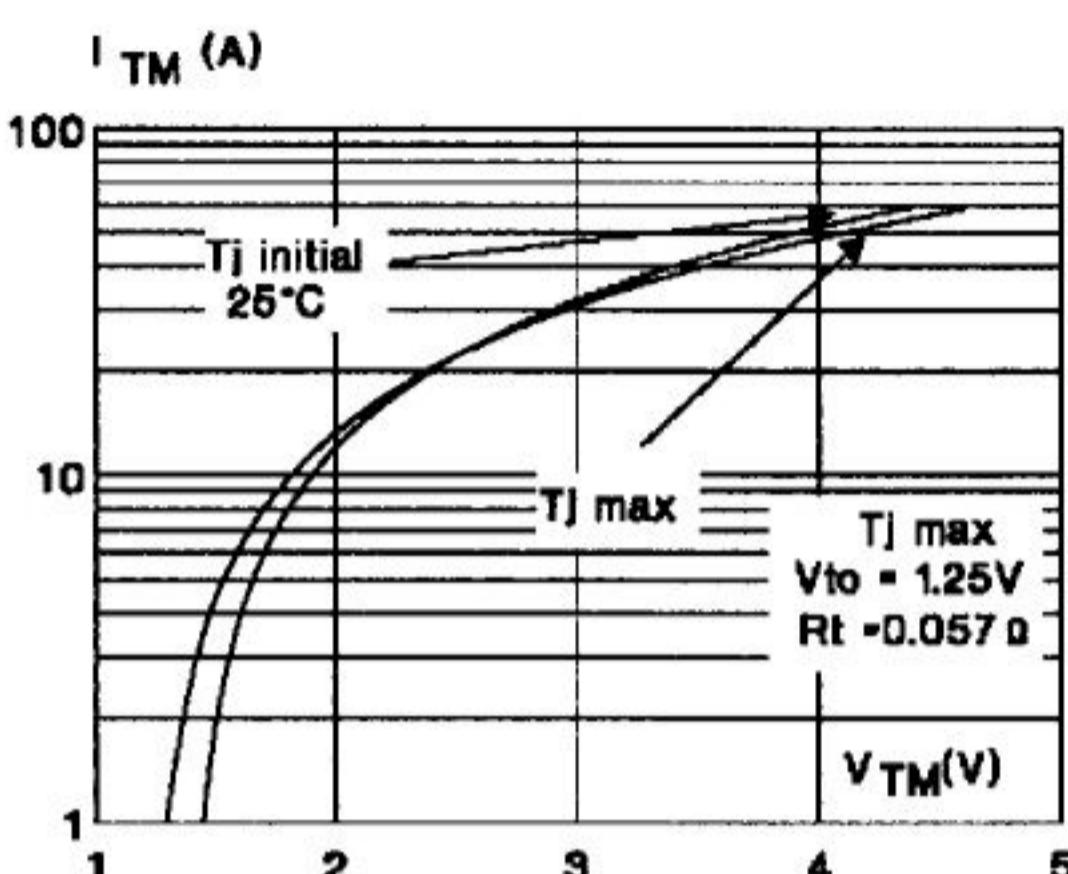


## TYN 204 ---> TYN 1004

**Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .**

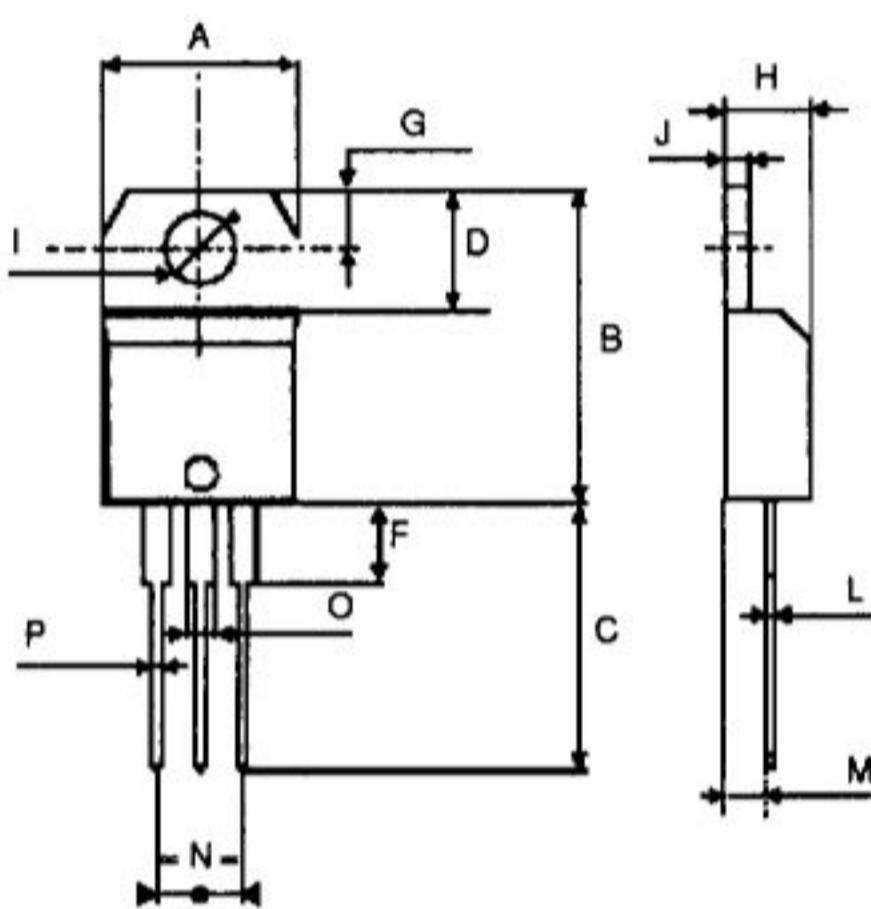


**Fig.8 : On-state characteristics (maximum values).**



## PACKAGE MECHANICAL DATA

TO220AB Plastic



Cooling method : C  
Marking : type number  
Weight : 2.3 g

Recommended torque value : 0.8 m.N.  
Maximum torque value : 1 m.N.

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